

IN THE CLAIMS:

Please cancel Claims 1 to 4, 7, 10 and 11 without prejudice or disclaimer of the subject matter presented therein and without conceding the correctness of their rejections. Please amend Claims 5, 6, 8 and 9 as shown below. The claims, as pending in the subject application, read as follows:

Sub P3
1 to 4. (Cancelled)

5. (Currently Amended) ~~A semiconductor~~ An image pickup apparatus comprising:
a lead of a flexible wiring ~~film~~; film;
~~a semiconductor device~~ an image pickup element chip electrically connected to the ~~lead~~, lead at an electrical connection point; and
a protecting member cover glass for protecting a surface of the ~~semiconductor device~~ image pickup element chip, which
wherein the lead, the image pickup element chip, and the cover glass are sealed with ~~a sealant~~ an ultraviolet-curing resin in a peripheral portion of ~~said~~ ~~semiconductor device~~ the image pickup element chip, and
wherein said the lead has a hole formed in a portion of the lead in contact with the ultraviolet-curing resin, the portion of the lead being between the electrical connection point and an outer end of the lead sealant.

B1

6. (Currently Amended) The semiconductor image pickup apparatus according to Claim 5, wherein at least a part of said the hole is formed in a region where a portion of the lead is sandwiched between said semiconductor device chip and said protecting member disposed between the cover glass and the ultraviolet-curing resin.

7. (Cancelled)

8. (Currently Amended) The semiconductor image pickup apparatus according to Claim 5, wherein at least one of a layer for preventing reflection of external light and a layer for preventing multiple reflection is formed between said the lead and said protecting member the cover glass.

9. (Currently Amended) An image pickup system comprising:
~~a solid-state image pickup apparatus consisting of the semiconductor apparatus as set forth in either one of Claims 5 to 8 the image pickup apparatus according to Claim 5;~~

~~an optical system for focusing light on said solid-state the image pickup apparatus; and~~

~~a signal processing circuit for processing an output signal from said solid state the image pickup apparatus.~~

10 and 11. (Cancelled)